

# RTI 900-1133 POGO PIN SOCKETS



## PRODUCT DATA SHEET

### PRODUCT OVERVIEW:

The RTI 900-1133 Series pogo pin sockets are designed to meet most low pin count FA or engineering requirements including: bench test, liquid crystal analysis, ESD testing, photo-emission, back-side emission, micro-probing, characterization, and engineering/production test. Detailed drawings are available upon request.

### FEATURES:

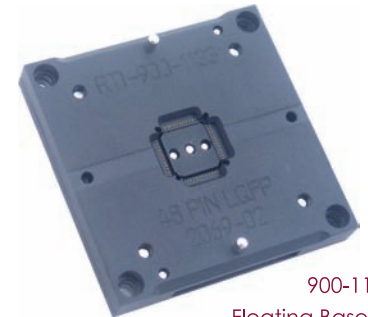
- ◆ Available for most packages from 1.0 mm to 22.0 mm body size
- ◆ Multiple standard lid sizes available
- ◆ Center ground pins if required
- ◆ Many types of pogo pins available
- ◆ Available for custom packages and pad configurations.
- ◆ Very low profile lid for micro-probing
  - ◆ 1.5 x 1.5 inches
  - ◆ Floating base design for BGA and QFP series

### AVAILABLE OPTIONS:

- ◆ Multiple center ground probes
- ◆ Open socket bases for back-side emission
- ◆ Heated sockets for liquid crystal analysis
- ◆ Heat sinks in base and lids
- ◆ Low inductance pins for RF characterization and test
- ◆ Pockets under sockets for component placement
- ◆ Multiple lid types (all fit the same base)

LID MODEL	DESCRIPTION
910-1001	FA screw-down open top lid
910-1002	Engineering dual latch lid
910-1013	Engineering/production push-down dual-latch clam shell
910-1027	Adjustable FA open top
910-1027 E	Adjustable Engineering
910-XXXX	Custom Lids

SERIES	DESIGN	PACKAGE TYPES
900-1133-QFN	Fixed Base Design	QFN, LLP, LGA, MLF and other leadless packages
900-1133-QFP	Floating Base Design	QFP, LQFP, TQFP, SOIC, and other leaded packages
900-1133-BGA	Floating Base Design	BGA, MicroBGA and other balled packages



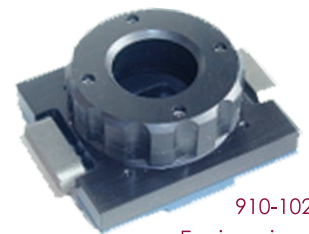
900-1133 QFP  
Floating Base Socket



910-1013  
Dual Latch  
Push Down  
Clam Shell Lid



910-1027  
FA Adjustable  
Clip-On-Open Top



910-1027E  
Engineering Lid



910-1001  
FA Screw Down Lid



900-1133  
Series Test Socket